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17. (Once amended) An edge bead remover configured to service a spinning wafer, comprising:

a nozzle configured to apply a solvent to an edge of said wafer; and
a vacuum mechanism enveloping said nozzle and offset from said edge during solvent application to said edge [a surface of said wafer].

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20. (Once amended) A material removal system for a wafer [having an edge], comprising:

a negative pressure device defining a vacuum area intersecting said wafer while said device is in an operational position [edge]; and
a solvent dispenser intersecting said vacuum area.

21. (Once amended) The material removal system of claim 20, wherein said negative pressure device is distal from said wafer while said device is in an operational position [edge].

22. (Once amended) An edge bead removal system for a wafer having an edge and a top and a bottom, comprising:

a first solvent nozzle poised above said top of said wafer at said edge during a dispensing mode of said system;
a second solvent nozzle poised below said bottom of said wafer at said edge during said dispensing mode; and
a suction device encompassing said first solvent nozzle and said second solvent nozzle.

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24. (Once amended) A chemical dispensing system for a workpiece, comprising:

a negative pressure device defining a portal disposed toward and spaced from [an edge of] all surfaces of said workpiece while acting upon said workpiece; and
a first solvent dispenser within said negative pressure device and disposed toward at least one surface of said workpiece while acting upon said workpiece [said edge].

25. (Once amended) The chemical dispensing system in claim 24, wherein said portal is spaced around [said] an edge of said workpiece.

28. (Once amended) A chemical remover for a substrate [edge], comprising:
a nozzle directed toward said substrate [edge] during a solvent dispensation mode and configured to couple to a solvent source; and
a vacuum device spaced from said substrate [edge] and directed toward said nozzle during said solvent dispensation mode.

29. (Once amended) A profiler for a wafer [edge], comprising:
a solvent dispenser perpendicular to said wafer during a fabrication process [edge]; and
a solvent vacuumer surrounding at least a portion of said solvent dispenser and separate from said wafer during said fabrication process [edge].

31. (Once amended) The profiler in claim 30, further comprising an additional solvent dispenser perpendicular to said wafer [edge]; wherein said solvent vacuumer surrounds at least a portion of said additional solvent dispenser.

32. (Once amended) The profiler in claim 31, wherein said solvent dispenser is disposed toward a top side of said wafer [edge].

33. (Once amended) The profiler in claim 32, wherein said additional solvent dispenser is disposed toward a bottom side of said wafer [edge].

REMARKS

Claims 1 and 12-43 were pending as of the Office Action dated March 21, 2000.

Claims 1 and 12-43 are subject to a restriction requirement.

Claims 1 and 12-43 are rejected.

Claims 1 and 34-43 are canceled.

Claims 12-14, 17, 20-22, 24-25, 28-29, and 31-33 are amended.